



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : LIN et al. Confirmation No: 2668
Appl. No. : 10/045,004
Filed : January 15, 2002
Title : LEAD-FREE SOLDER

TC/A.U. : 1742
Examiner : S. Ip

Docket No.: : LINK3019/REF
Customer No: : 23364

AMENDMENT AFTER FINAL

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of March 23, 2004, in connection with the above-identified application. This response is timely filed.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 3 of this paper.